Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]
HP EliteDesk 800 G4 SFF

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Chicony 250W EPA92 HV :C1</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink,</td>
<td>Include the cartridges, print heads, tubes, vent</td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#)
including liquids, semi-liquids (gel/paste) and toner chambers, and service stations.

| Components and waste containing asbestos | 0 |
| Components, parts and materials containing refractory ceramic fibers | 0 |
| Components, parts and materials containing radioactive substances | 0 |

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 Screw Driver, Cross Type</td>
<td></td>
</tr>
<tr>
<td>Description #2 Cut-Pliers, Small Size</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

#### 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Slide the latch and remove access panel. (see Figure 1-2 below)
2. Rotate the driver cage form the hook on slide rail. (see Figure 3 below)
3. Disconnect power cable from the MB. (see Figure 4 below)
4. Disconnect SATA cables from the MB. (see Figure 5 below)
5. Disconnect speaker cable from the MB. (see Figure 6 below)
6. Disconnect other PSU cables from the MB. (see Figure 7-8 below)
7. Remove the fan duct (see Figure 9-10 below)
8. Disconnect P3 cable from MB. (see Figure 11 below)
9. Remove HDD/ODD from chassis. (see Figure 12-19 below)
10. Remove the heatsink from MB. (see Figure 20-21 below)
11. Separate the fan from CPU heatsink. (see Figure 22 below)
12. Remove the memory card from the MB. (see Figure 23 below)
13. Remove the CPU from the MB. (see Figure 24-25 below)
14. Remove M/B from chassis. (see Figure 26-27 below)
15. Remove the battery from MB. (see Figure 28 below)
16. Remove LED holder from MB. (see Figure 29 below)
17. Remove front panel from chassis. (see Figure 30 below)
18. Remove Speaker from chassis. (see Figure 31 below)
19. Unscrew the PSU and disconnect all PSU cables from chassis. (see Figure 32-35 below)
20. Remove PSU cover and remove the Electrolytic Capacitors. (see Figure 36-41 below)

#### 3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01).
Figure 7 Disconnect P1 power cable from the MB

Figure 8 Disconnect P2 power cable from MB

Figure 9 press the hook and pull up the fan duct

Figure 10 Remove the fan duct

Figure 11 Disconnect P3 Power cable from MB

Figure 12 Pull the HDD latch and rotate the HDD up

PSG instructions for this template are available at EL-MF877-01
Figure 13 Disconnect power cable from HDD
Figure 14 Disconnect SATA cable from HDD
Figure 15 Remove the HDD from HDD cage
Figure 16 Disconnect power cable from ODD
Figure 17 Disconnect SATA cable from ODD
Figure 18 Press the ODD latch and remove it

PSG instructions for this template are available at [EL-MF877-01](#)
Figure 19 Remove ODD from ODD cage

Figure 20 Disconnect CPU fan cable from MB

Figure 21 Use T15 screwdriver to unscrew the screw and remove the heatsink

Figure 22 Use PH1 screwdriver to break up the heatsink into fan and cooler
PSG instructions for this template are available at [EL-MF877-01](#).
Step 29 Remove LED cover from MB

Step 30 Remove the front bezel

Step 31 Use T15 screwdriver remove speaker from the front wall

Step 32 Use T15 screwdriver to remove the PSU screws from rear wall

Step 33 Remove all the power cables from the hook

Step 34 Press the latch and slide the PSU out

PSG instructions for this template are available at [EL-MF877-01](#)
Step 35 Remove the PSU from chassis

Step 36 De-screwed from the external case top, use tool #1

Step 37 De-screwed from the external case bottom, use tool #1

Step 38 Remove the external case of back side

PSG instructions for this template are available at [EL-MF877-01](#)
<table>
<thead>
<tr>
<th>Step 39</th>
<th>Step 40</th>
</tr>
</thead>
<tbody>
<tr>
<td>De-screwed from the main PCBA (solder side), use tool #1</td>
<td>Pull-off the connectors/housings</td>
</tr>
<tr>
<td>Step 41</td>
<td></td>
</tr>
<tr>
<td>Cut-off and remove the biggest electrolyte capacitor(C1), use tool #2</td>
<td></td>
</tr>
</tbody>
</table>

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